

L Number	Hits	Search Text	DB	Time stamp
1	3	wafer and (polymer\$4 with cap\$4) and ((eject\$4 or project\$4) adj pin\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 09:41
2	306	wafer and ((eject\$4 or project\$4) adj pin\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 09:42
3	206	(wafer and ((eject\$4 or project\$4) adj pin\$4)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 09:42
4	31	((wafer and ((eject\$4 or project\$4) adj pin\$4)) and semiconductor) and (led\$4 or (light adj emitting adj device\$2))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 11:06
5	2	"20030123816"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 09:58
6	2	"20020117623"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 09:59
7	16	"6001664"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:02
8	32	"5500540"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:10
9	9	"5805757"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:10
10	18	"5521123"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:26
11	4	"6429506"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:31
12	6	"5789307"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:32

13	10	"6255741"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:35
14	151	"4483194"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:38
15	23	"4483194" and pin\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 10:38